



HLMC2012S

FEATURES 特性

1. High common mode impedance at high frequency effects excellent noise suppression performance.
高频共模阻抗高，噪声抑制性能优良。
2. 20Ω~2000Ω are optional for different noise level and signal frequency
对于不同的噪声电频和信号频率，选择20Ω~2000Ω阻抗。

APPLICATIONS 用途

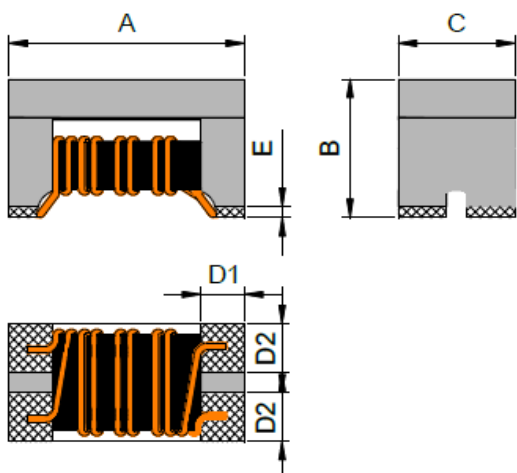
1. USB 2.0 line for personal computers and peripheral
电脑和外围设备的USB 2.0线路。
2. IEEE 1394 line for personal computers, DVC, STB
用于计算机、DVC、机顶盒的IEEE 1394线路。
3. LVDS, panel line for liquid display panels, graph card, etc.
LVDS，用于液体显示面板的面板线，图形卡等。

PART NUMBERING SYSTEM 品名系统

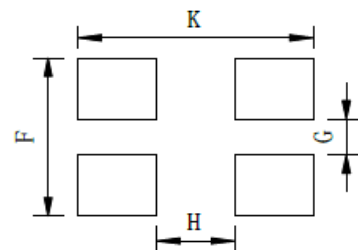
HLMC 3216 S - 900 - 2P - I
 A B C D E F

A: Type 型号 B: External Dimensions 外形尺寸 A*C
 C: Material type 材料类型 D: Impedance Value 阻抗值 900 = 90Ω
 E: Number of line 2P : 2-Line 双线 F: Packaging : T=Taping and reel

SHAPES AND DIMENSIONS 外形尺寸 (Unit:mm)



Recommended Land Pattern

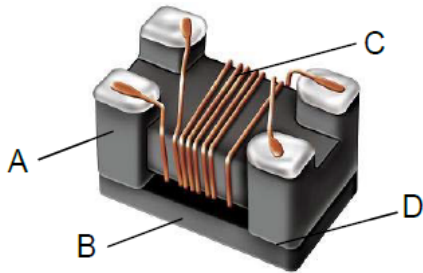


TYPE(型号)	A	B	C	D1	D2	E	F	G	H	K
HLMC2012S	2.0±0.2	1.2±0.2	1.2±0.2	0.5 Ref	0.45 Ref	0.17 Max	1.2 Ref	0.4 Ref	0.8 Ref	2.0 Ref



Product title	Size (LxWxH)	Rated current
HLMC2012S	2.0±0.2mm/1.2±0.2mm/1.2±0.2mm	450~150mA

STRUCTURE AND MATERIAL 结构与材料



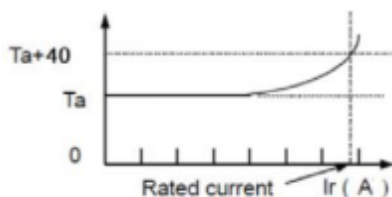
Part	Components	Material
A	Core	Ferrite
B	I Core	Ferrite
C	Wire	Polyurethane enameled copper wire
D	Epoxy	Epoxy resin

ELECTRICAL CHARACTERISTICS 电特性

1. Operating temperature range : -40 ~ 85 (Including self - temperature rise)
2. Storage temperature range (packaging conditions): -10 ~+40 and RH 70% (Max.)

TEST AND MEASUREMENT PROCEDURES 测试和测量程序

1. Common Mode Impedance(Ω)
Test equipment: Keysight E4991B / Agilent 4787A or equivalent
2. DC Resistance (DCR)
Test equipment: Agilent34420A / Agilent 4338B or equivalent
3. Rated Current (Irms)
Irms is direct electric current as chip surface temperature rose just 40 against chip initial surface temperature (Ta)



4. Insulation Resistance
Test equipment: Chroma or equivalent TH2683A / ZX6583

RECOMMENDED SOLDERING TECHNOLOGIES 推荐的焊接技术

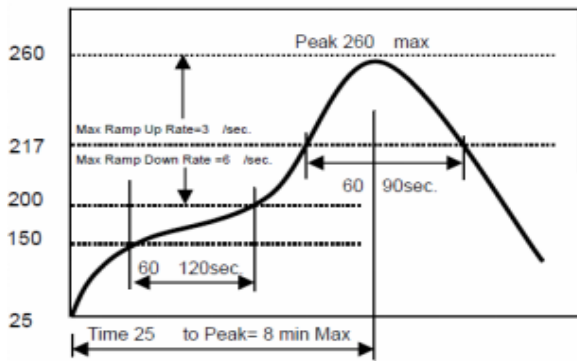
Re-flowing Profile

Preheat condition: 150~200 /60~120sec. Allowed time above 217C: 60~90sec.

Max temp: 260

Max time at max temp: 10sec Solder paste: Sn/3.0Ag/0.5Cu Allowed

Reflow time: 2 times max



SPECIFICATION TABLE:

HLMC2012S Series

Part No.	Common Model Impedance(Ω)	Test Frequency(MHz)	DCR (Ω) Max	Max. Rated Current (mA)	Rated Voltage(Vdc)	Insulation Resistance(M Ω) Min.
HLMC2012S-300-2P-T	30 \pm 25%	100	0.20	450	50	10
HLMC2012S-670-2P-T	67 \pm 25%	100	0.25	400	50	10
HLMC2012S-750-2P-T	75 \pm 25%	100	0.30	400	50	10
HLMC2012S-900-2P-T	90 \pm 25%	100	0.30	330	50	10
HLMC2012S-121-2P-T	120 \pm 25%	100	0.30	370	50	10
HLMC2012S-181-2P-T	180 \pm 25%	100	0.35	330	50	10
HLMC2012S-201-2P-T	200 \pm 25%	100	0.35	330	50	10
HLMC2012S-221-2P-T	220 \pm 25%	100	0.40	300	50	10
HLMC2012S-261-2P-T	260 \pm 25%	100	0.40	300	50	10
HLMC2012S-371-2P-T	370 \pm 25%	100	0.45	280	50	10
HLMC2012S-601-2P-T	600 \pm 25%	100	0.60	220	50	10
HLMC2012S-751-2P-T	750 \pm 25%	100	0.70	180	50	10
HLMC2012S-801-2P-T	800 \pm 25%	100	0.75	160	50	10
HLMC2012S-901-2P-T	900 \pm 25%	100	0.80	150	50	10
HLMC2012S-102-2P-T	1000 \pm 25%	100	0.80	150	50	10



1. Operating temperature range : -40 ~ 85 (Including self - temperature rise)
2. Storage temperature range (packaging conditions): -10 ~+40 and RH 70% (Max.)
3. Rated Current (Irms)
Irms is direct electric current as chip surface temperature rose just 40 against chip initial surface temperature (Ta)